

S/N 10/723,474

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon Examiner: DiLinh Nguyen
Serial No.: 10/723,474 Group Art Unit: 2814
Filed: November 26, 2003 Docket No.: 303.601US2
Title: ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM
WAFER LEVEL PACKAGING

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on December 13, 2007. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office Action, thereby moving the deadline for response from March 13, 2008 to April 13, 2008 (Sunday).